ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises a semiconductor chip having a plurality of electrodes formed in a first major surface thereof, a resin package sealing the semiconductor chip therein, a plurality leads electrically connected to the electrodes of the semiconductor chip and formed so as to extend inside and outside the resin package, and a support lead supporting the semiconductor chip at a part of a second major surface of the semiconductor chip opposite the first major surface. The semiconductor chip is bonded to the support lead with an adhesive tape.

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